



Material Content Data Sheet



Sales Product Name		BSC042NE7NS3 G		Issued		24. January 2018		
MA#		MA001507780						
Package		PG-TDSON-8-39		Weight*		121.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	3.62	3.62	36245	36245
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		310	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93	
	non noble metal	copper	7440-50-8	37.762	30.99	31.03	310078	310481
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	470	470
encapsulation	organic material	carbon black	1333-86-4	0.079	0.07		652	
	plastics	epoxy resin	-	6.275	5.15		51529	
	inorganic material	silicondioxide	60676-86-0	33.362	27.40	32.62	273954	326135
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11920	11920
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1359	1359
solder	noble metal	silver	7440-22-4	0.087	0.07		714	
	non noble metal	tin	7440-31-5	0.070	0.06		571	
	non noble metal	lead	7439-92-1	3.322	2.73	2.86	27275	28560
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.30	9.31	92954	93075
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	noble metal	silver	7440-22-4	1.032	0.85		8471	
	non noble metal	copper	7440-50-8	22.292	18.30	19.18	183046	191755
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com